

MATERIAL DECLARATION SHEET



Material Number	CRT1206A Series			
Product Line	Thick Film Chip Resistors			
Compliance Date	2021/06/11			
RoHS Compliant	Yes	MSL	1/2/3	

No.	Construction Element(subpart)	Homogeneous Material	Material weight [mg]	Homogeneous Material\ Substances	CASRN if applicable	Material s Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Ceramic Substrate	Ceramic	7.78984	Aluminum oxide	1344-28-1	96%	81.96%	85.37%
				Silicon dioxide	14808-60-7	4%	3.41%	
2	Conductor Layer	Ag Alloy	0.03649	Silver	7440-22-4	95%	0.38%	0.40%
				Glass	65997-17-3	5%	0.02%	
3	Resistive Element	Ni-Cr	0.02919	Nickel	7440-02-0	45%	0.14%	0.32%
				Chromium	7440-47-3	55%	0.18%	
4	Over-Coating	Epoxy	0.32941	Epoxy	29690-82-2	100%	3.61%	3.61%
5	Over Coating	Epoxy	0.34856	Epoxy	25068-38-6	100%	3.82%	3.82%
6	Marking	Epoxy	0.01094	Epoxy	25085-99-8	100%	0.12%	0.12%
7	End Terminal	Ni-Cr	0.00821	Nickel	7440-02-0	80%	0.07%	0.09%
				Chromium	7440-47-3	20%	0.02%	
8	Ni Plating	Nickel	0.30203	Nickel	7440-02-0	100%	3.31%	3.31%
9	Sn Plating	Tin	0.27009	Tin	7440-31-5	100%	2.96%	2.96%
		Total	9.12476					

This Document was updated on: 2021/06/11

Important remarks: It is the responsibility of the user to verify they are accessing the latest version.